



## Final Product Change Notification

201607038F01

**Issue Date:** 31-Aug-2016  
**Effective Date:** 28-Nov-2016

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# QUALITY

### Management Summary

Qualification of KESM (Malaysia) as a second test source for 7x7 TPMS products to improve overall capacity and provide manufacturing flexibility.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Process	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Equipment	<input checked="" type="checkbox"/> Electrical spec./Test coverage

TPMS 7x7, FXTH87 Family, Test and Burn-in Expansion to KES (Malaysia)

### Details of this Change

NXP is announcing the final test and burn in site expansion for the FXTH87 family of 7x7 TPMS devices from the current ASE-CL (Taiwan) site to the KES (Malaysia) site.

The equivalent final test flows, tester, handler and software currently used in the ASE-CL (Taiwan) site will be implemented at the KES (Malaysia) site. The following changes are included.

1. Site expansion will include an increase in parallelism at final test.
2. NXP will be using its ATKL factory for dry pack and tape and reel, which includes a change to the reel and shipping material. The tape leader and trailer lengths will also differ. These changes are reflected in the enclosed packaging and shipping comparison.
3. The internal serial ID will be modified to differentiate test location, affecting ID31:ID28. See enclosed serial ID format document and product specification addendums for full description of these changes.

### Why do we Implement this Change

Qualification of the KES (Malaysia) final test and burn in site to improve manufacturing flexibility and customer supply assurance.

### Identification of Affected Products

Product identification does not change

### Product Availability

**Sample Information**

Samples are available upon request

**Production**

Planned first shipment 15-Sep-2016

**Impact**

no impact to the product's functionality anticipated.

**Data Sheet Revision**

A new datasheet will be issued

**Disposition of Old Products**

Product will now be available from this location in addition to the existing test site

**Timing and Logistics**

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 30-Sep-2016.

**Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Jason Diefenbacher

**Position** Product Engineer

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
FXTH870902DT1	FXTH870902DT1	FXTH870902DT1	TPMS 7X7 900KPA Z AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH871511DT1	FXTH871511DT1	FXTH871511DT1	TPMS 7X7 1500KPA XZ AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH870911DT1	FXTH870911DT1	FXTH870911DT1	TPMS 7X7 900KPA X&Z AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH8715026T1	FXTH8715026T1	FXTH8715026T1	TPMS 7X7 1500KPA Z AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH8715116T1	FXTH8715116T1	FXTH8715116T1	TPMS 7X7 1500KPA XZ AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH8715117T1	FXTH8715117T1	FXTH8715117T1	TPMS 7X7 1500KPA XZ AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH870912DT1	FXTH870912DT1	FXTH870912DT1	TPMS 7X7 900KPA XZ AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH870502DT1	FXTH870502DT1	FXTH870502DT1	TPMS 7X7 450KPA Z AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH8709226T1	FXTH8709226T1	FXTH8709226T1	TPMS 7X7 900KPA XZ AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH871502DT1	FXTH871502DT1	FXTH871502DT1	TPMS 7X7 1500KPA Z AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors
FXTH870511DT1	FXTH870511DT1	FXTH870511DT1	TPMS 7X7 450KPA X&Z AXIS	QFN-EP MAP 24 7*7*2.2 P1	QFN-EP MAP 24 7*7*2.2 P1	RFS	BL Analog & Sensors